



## Deep-Access & Ball-Wedge Bonder 53xxBDA

### Bond System

<b>Wire types</b>	Gold wire 17,5-50µm on 2" spool Aluminium wire 17,5-75µm on 2" spool Ribbons from 30x12,5µm up to 250x25µm
<b>Bondhead</b>	Ball-Wedge & Deep-Access for Au & Alu wire Standard tool 16mm (optional 19mm) Motorized wire spool (optional)
<b>Ultrasonic System</b>	F&S Generator 67kHz (optional 100, 120, 140kHz)

### Bonder Base

#### Axes

- Programmable linear Z-axis with 60mm stroke
- Programmable linear Y-axis with 20mm stroke
- Standard working height: 55 mm
- Manipulator in X and Y: 18x18 mm
- Equivalent to: 1: 7

#### Hardware

- Stepper motor driven Z-linear axis,
- Single-board PC, coin-guided teach-in,
- Internal hard disk, operation and menu-guided via shuttle wheel with confirmation button

#### Software

- Programmable single Bonds
- Loop shapes can be saved

**Control** Manual, semi-automatic

**Dimensions** W x D x H – 63 x 58 x 40 cm, weight approx. 30kg

**Connections** 100-230 VAC, 1 Phase, 50/60 Hz, max 230 VA  
Ø 6mm standard-vacuum tubing

**Heater controller** integrated in the machine 0-250 °C

### The 53xx Series:

Our manual/semiautomatic universal thin wire bonder 53XX BDA is the perfect choice for R&D labs, prototype building and re-pair facilities whenever highest bond quality is required but only a limited budget is available.

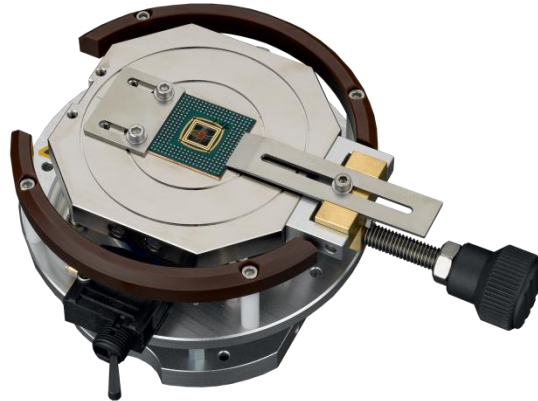
It offers two bond processes in one bond-head: gold ball-bonding and deep-access wedge bonding. Switching over could not be simpler: just move the flame-off unit back, insert the wire clamp and replace the bond capillary with a wedge and you are ready to go.

The second unique feature of the 53XX BDA is the built-in motorized Y-axis. It is fully programmable and produces an entire bond loop, complete with programmable tear-off function and tail definition. Especially for miniaturized micro-wave bonds, this guarantees perfectly reproducible bonds with no operator influence.

Even for thicker wires, the cascading clamp system with one clamp above the wedge and a second clamp at the wedge foot ensures that the wire tear-off is reliable and constant.

## Workholder

Standard-Workholder  
With mechanical clamping  
Ø80mm



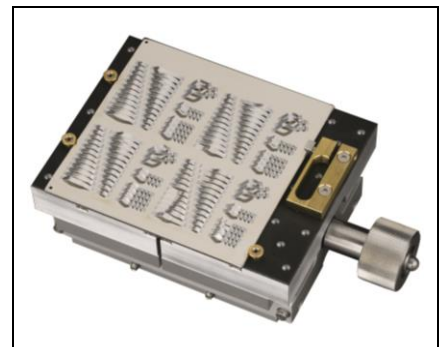
## Optional:



workholder for parts up to 4x4"  
with vacuum and mechanical  
clamping



TO workholder with  
mechanical clamping



4x4" workholder with  
rubbered surface and  
mechanical clamping

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